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DOC.

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Midas 2006 version logo. Midas is an integrated manufacturer of flat panel display (FPD). Midas supplies TN, HTN, STN, FSTN monochrome LCD panel; COB, COG, TAB LCD module; and all kinds of LED backlight.



#### **FAST RESPONSE TIME**

This icon on the cover indicates the product is with high response speed; Otherwise not.



#### PROTECTION CIRCUIT

This icon on the cover indicates the product is with protection circuit; Otherwise not.



#### **HIGH CONTRAST**

This icon on the cover indicates the product is with high contrast; Otherwise not.



#### LONG LIFE VERSION

This icon on the cover indicates the product is long life version (over 9K hours guaranteed); Otherwise not.



#### WIDE VIEWING SCOPE

This icon on the cover indicates the product is with wide viewing scope; Otherwise not.



#### **Anti UV VERSION**

This icon on the cover indicates the product is against UV line. Otherwise not.



#### **RoHS COMPLIANCE**

This icon on the cover indicates the product meets ROHS requirements; Otherwise not.



#### **OPERATION TEMPERATURE RANGE**

This icon on the cover indicates the operating temperature range (X-Y).



#### **3TIMEs 100% QC EXAMINATION**

This icon on the cover indicates the product has passed Midas thrice 100% QC.
Otherwise not.



#### TWICE SELECTION OF LED MATERIALS

This icon on the cover indicates the LED had passed Midas twice strict selection which promises the product's identical color and brightness; Otherwise not.



#### Vlcm = 3.0V

This icon on the cover indicates the product can work at 3.0V exactly; otherwise not.



#### N SERIES TECHNOLOGY (2008 developed)

New structure, new craft, new technology and new materials inside both LCD module and LCD panel to improve the "RainBow"

### MC22405C6WK-SPTLY

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# 1. Specification Revision History

	RECORDS OF REVISION													
VERSION	DATE	REVISED PAGE NO.	Note											
1	2008.04.07		First issue											



### 2. General Specification

The Features of the Module is description as follow:

■ Module dimension: 118.0 x 36.0 x 13.6 (max.) mm<sup>3</sup>

■ View area: 94.5 x 16.0 mm<sup>2</sup>

Active area:  $88.3 \times 11.5 \text{ mm}^2$ 

■ Number of Characters: 24 characters x 2 Lines

■ Dot size:  $0.6 \times 0.65 \text{ mm}^2$ 

■ Dot pitch:  $0.65 \times 0.70 \text{ mm}^2$ 

■ Character size: 3.2 x 5.55 mm<sup>2</sup>

■ Character pitch: 3.7 x 5.95 mm<sup>2</sup>

■ LCD type: STN Positive, Yellow Green Transflective

■ Duty: 1/16

■ View direction: 6 o'clock

■ Back<mark>light Type: LED Yellow Green</mark>

### **Midas LCD Part Number System**

#### COG 132033 MC S Т 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16

- 1 = MC: Midas Components
- 2 = **Blank:** COB (chip on board) **COG**: chip on glass
- 3 = No of dots (e.g.  $240064 = 240 \times 64 \text{ dots}$ ) (e.g.  $21605 = 2 \times 16 \text{ 5mm C.H.}$ )
- 4 = Series
- 5 = Series Variant: A to Z
- 6 = **3:** 3 o'clock **6:** 6 o'clock **9:** 9 o'clock **12:** 12 o'clock
- 7 = S: Normal (0 to + 50 deg C) W: Wide temp. (-20 to + 70 deg C) X: Extended temp (-30 + 80 Deg C)
- 8 = Character Set

Blank: Standard (English/Japanese)

C: Chinese Simplified (Graphic Displays only)

CB: Chinese Big 5 (Graphic Displays only)

H: Hebrew

K: European (std) (English/German/French/Greek)

L: English/Japanese (special)

M: European (English/Scandinavian)

R: Cyrillic

W: European (English/Greek)

U: European (English/Scandinavian/Icelandic)

#### 9 = Bezel Height (where applicable / available)

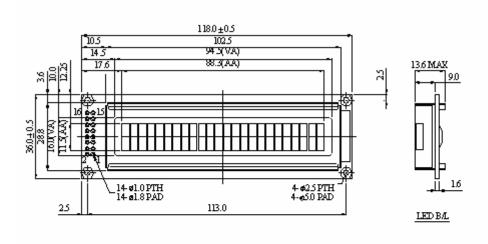
	Ton of Paral to Ton	Common	Array
	Top of Bezel to Top of PCB	(via pins 1	or Edge
		and 2)	Lit
Blank	9.5mm / not applicable	Common	Array
2	8.9 mm	Common	Array
3	7.8 mm	Separate	Array
4	7.8 mm	Common	Array
5	9.5 mm	Separate	Array
6	7 mm	Common	Array
7	7 mm	Separate	Array
8	$6.4 \mathrm{\ mm}$	Common	Edge
9	6.4 mm	Separate	Edge
$\mathbf{A}$	5.5 mm	Common	$\mathbf{Edge}$
В	5.5  mm	Separate	Edge

- 10 = **T:** TN **S:** STN **B:** STN Blue **G:** STN Grey **F:** FSTN **F2:** FFSTN
- 11 = P: Positive N: Negative
- 12 = **R:** Reflective **M:** Transmissive **T:** Transflective
- 13 = **Backlight: Blank:** Reflective **L:** LED
- = Backlight Colour: Y: Yellow-Green W: White B: Blue R: Red A: Amber O: Orange G: Green RGB: R.G.B.
- 15 = **Driver Chip:** Blank: Standard I: I<sup>2</sup>C
- 16 = Voltage Variant: e.g. 3 = 3v

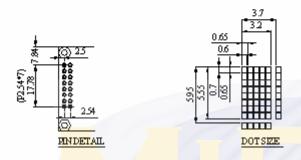
### 4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	$V_{SS}$	0V	Ground
2	$V_{\mathrm{DD}}$	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read(MPU→Module) L: Write(MPU→Module)
6	E	Н,Н→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	A		Power supply for LED backlight (+)
16	K	_	Power supply for LED backlight ( - )

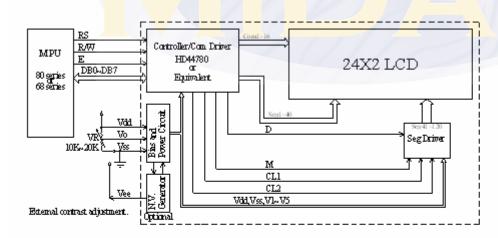
## 5. Contour Drawing & Block Diagram



MM NO.	SYMBOL.
1	Vss
2	Vdd
3	Vo
4	RS
5	R∕W
6	E
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7
15	A
16	K



The non-specified tolerance of dimension is  $\pm 0.3$ mm.



Character located 1 2 3 4 5 6 ----- 19 20 21 22 23 24

DDRAM address 00 01 02 03 04 05 ----- 12 13 14 15 16 17 DDRAM address 40 41 42 43 44 45 ------ 52 53 54 55 56 57

### **6. Function Description**

The LCD display Module is built in a LSI controller, the controller has two 8-bit registers, an instruction register (IR) and a data register (DR).

The IR stores instruction codes, such as display clear and cursor shift, and address information for display data RAM (DDRAM) and character generator (CGRAM). The IR can only be written from the MPU. The DR temporarily stores data to be written or read from DDRAM or CGRAM. When address information is written into the IR, then data is stored into the DR from DDRAM or CGRAM. By the register selector (RS) signal, these two registers can be selected.

RS	R/W	Operation
0	0	IR write as an internal operation (display clear, etc.)
0	1	Read busy flag (DB7) and address counter (DB0 to DB7)
1	0	Write data to DDRAM or CGRAM (DR to DDRAM or CGRAM)
1	1	Read data from DDRAM or CGRAM (DDRAM or CGRAM to DR)

#### **Busy Flag (BF)**

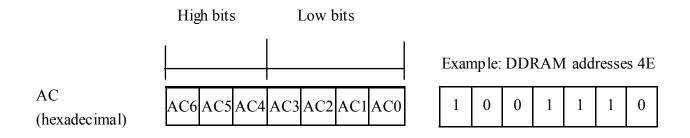
When the busy flag is 1, the controller LSI is in the internal operation mode, and the next instruction will not be accepted. When RS=0 and R/W=1, the busy flag is output to DB7. The next instruction must be written after ensuring that the busy flag is 0.

#### Address Counter (AC)

The address counter (AC) assigns addresses to both DDRAM and CGRAM.

#### **Display Data RAM (DDRAM)**

This DDRAM is used to store the display data represented in 8-bit character codes. Its extended capacity is 80×8 bits or 80 characters. Below figure is the relationships between DDRAM addresses and positions on the liquid crystal display.



#### Display position DDRAM address

1	2	3	4	5	6	7	 21	22	23	24

00	01	02	03	04	05	06			14	15	16	17
40	41	42	43	44	45	46			54	55	56	57

2-Line by 24-Character Display

#### **Character Generator ROM (CGROM)**

The CGROM generate  $5\times8$  dot or  $5\times10$  dot character patterns from 8-bit character codes. See Table 2.

#### **Character Generator RAM (CGRAM)**

In CGRAM, the user can rewrite character by program. For  $5\times8$  dots, eight character patterns can be written, and for  $5\times10$  dots, four character patterns can be written.

Write into DDRAM the character code at the addresses shown as the left column of table 1. To show the character patterns stored in CGRAM.

### Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character patterns

Table 1.

For

5 * 8 dot character patte	ns		
Character Codes (DDRAM data)	CGRAM Address	Character Patterns (CGRAM data)	
7 6 5 4 3 2 1 0	5 4 3 2 1 0	7 6 5 4 3 2 1 0	
High Low	High Low	High Low	
0 0 0 0 * 0 0 0	0 0 0 0 0 0 0 1 0 0 1 1 0 0 1 1 1 1 1 0 1 1 1 0 0 0 0 0 0 0 0	* * * * * * * * * * * * * * * * * * *	Character pattern(1)
0 0 0 0 * 0 0 1	0 0 1 0 0 1 0 1 0 0 1 1 0 0 1 1 1 0 0 1 1 1 0 1 1 1 0	* * * * 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	C haracter pattern(2)
	0 0 1		
0 0 0 0 * 1 1 1	1 1 1 1 0 0 1 0 1 1 1 0 1 1 1	* * *	
* 10 dot character patte	rns		
Character Codes (DDRAM data)	CGRAM Address	Character Patterns (CGRAM data)	
7 6 5 4 3 2 1 0	5 4 3 2 1 0	7 6 5 4 3 2 1 0	

For 5

J TO dot character pat	10 11	1.0		
Charac <mark>ter Codes</mark> (DDRAM data)		CGRAM Address		Character Patterns (CGRAM data)
7 6 5 4 3 2 1 0		5 4 3 2 1 0		7 6 5 4 3 2 1 0
High Low		High Low		H igh Low
0 0 0 0 * 0 0 0		0 0 0 0 0 0 0 0 0 0 0 0 1 0 0 0 1 0 0 0 1 0		* * * 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0
		1 1 1 1	$\vdash$	* * * * * * *

■ : " H ig h "

### 7. Character Generator ROM Pattern

Table 2.

Upper 4 bit Lower 4 bit	LLLL			LLHH	LHLL			LHHH		HLLH			HHLL	HHLH	НННЬ	нннн
LLLL	CG RAM (1)				TAR		11 Th	, , , , , , , , , , , , , , , , , , ,		nøfen Jana Lanør		×	A . Tayan galampalan			
LLLH	CG RAM (2)						1/1 11/1 11/1 11/1					#	primepiones inper in in			
LLHL	CG RAM (3)			Agene Page Agene	insa insa i i i i i i i i i i i i i i i i i i i			},""			▗▗▘ █ <mark>▄▄</mark> ░ੑੑੑੑੑੑੑ	er er e			RR_ RE	
LLHH	CG RAM (4)					HERU HERE HERE HERE	n i in H H H	, 1) 1) II " 11 11 II " 11 11 II	taf anns anns	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	▗▗▘ █ <sub>▃▄</sub> ▗}	•			, nun }	
LHLL	CG RAM (5)	1								E NAME OF THE PROPERTY OF THE		**	a į į ak			B <sub>n</sub> n <sub>1</sub> g
LHLH	CG RAM (6)				Panar Panar			}     £ ``n,a=B				EDI EL ET III Ampiat				
LHHL	CG RAM (7)	A SECTION ASSESSMENT OF SECTION ASSESSMENT A						1,,,1		a"r E.,a <mark>l</mark>	¥					
LHHH	CG RAM (8)								A MATERIAL PARTY AND PARTY				A PROPERTY OF THE PROPERTY OF	I TE	1	
HLLL	CG RAM (1)		Ç					" , , , , , , , , , , , , , , , , , , ,			<b>.</b> F`	11, 100, 11, 11, 11, 11, 11, 11, 11, 11, 11,	n   jan		<b>}</b> =:,	
HLLH	CG RAM (2)			MM P				u u u u u di u u u di u u u		Pana Rana B B Pana	) I					
HLHL	CG RAM (3)	n" n " n" n "	<b>*</b>				, "Ì	111 <u>1</u>			~==,` {==,`	estans P P P			<u> </u> ,	
НЦНН	CG RAM (4)		rajhan H				} } !*** !****		n/Sin.	~** <u>*</u>						
HHLL	CG RAM (5)	<b></b>	<b>74</b>			****	1			╻ <sup>┺┸</sup> ╻ <sup>╸</sup> ┠ <sup>┺</sup> ┺╻┇ ┇					, <u>.</u>	
ННГН	CG RAM (6)	,	n numu	1222		.,,		l ' '		nnni Povol Nasal	nang Pang Pang		Ħ		12 13 1 13 1 13,	<del>1111</del> )
HHHL	CG RAM (7)		12			<b></b>		1 <sup>2</sup> 1 <sub>3</sub> 2				H Americani eta Americani eta			""      	
нннн	CG RAM (8)		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,				<b>™</b> ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™ ™		, a, , a, , a, a, , a, a, a, a,	n n <sup>n</sup> B <sub>nnn</sub> s			,	▗▝▀▗▀ ▋ <sub>▜</sub> ▓█ <sub>▓</sub>	, nago i , at	

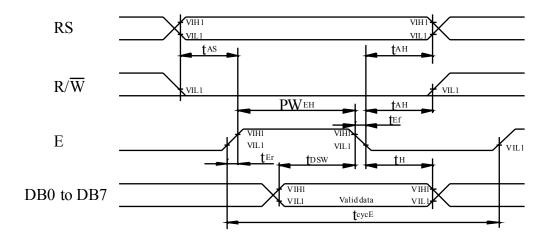
### 8. Instruction Table

Instruction				Ins	structi	ion Co	de				Description	Execution time	
Thstruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	-	(fosc=270Khz)	
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "00H" to DDRAMand set DDRAM address to "00H" from AC	1.53ms	
Retum Home	0	0	0	0	0	0	0	0	1	l	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.53ms	
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Assign cursor moving direction and enable the shift of entire display.	39 μ s	
Display ON/OFF Control	0	0	0	0	0	0	1	D	С	В	Set display (D), cursor (C), and blinking of cursor (B) on/off control bit.	39 μ s	
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	_	_	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	39 μ s	
Function Set	0	0	0	0	1	DL	N	F	7		Set interface data length (DL:8-bit/4-bit), numbers of display line (N:2-line/1-line)and, display font type (F:5×11 dots/5×8 dots)	39 μs	
Set CGRAM Address	0	0	0	1	AC5	A <mark>C4</mark>	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	39 μs	
Set DDRAM Address	0	0	1	AC6	AC5	A <mark>C4</mark>	AC3	AC2	AC1	AC0	Set DDRAM address in address counter.	39 μs	
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0 μ s	
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	43 μs	
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	43 μs	

\* "-": don't care

# 9. Timing Characteristics

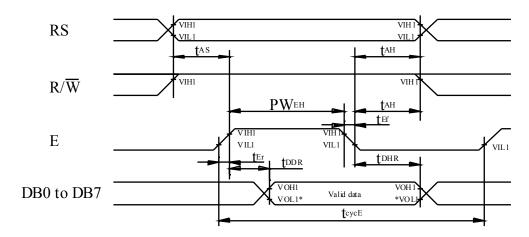
### 9.1 Write Operation



Ta=25°C, VDD= $5.0\pm0.5$ V

					= /
Item	<mark>Sym</mark> bol	M in	Тур	Max	Unit
Enable cyc <mark>le t</mark> ime	t <sub>cycE</sub>	1200			ns
Enable pulse width (high level)	PW <sub>EH</sub>	140			ns
Enable rise/fall time	$t_{\rm Er}, t_{\rm Ef}$	1		25	ns
Address set-up time (RS, R/W to E)	$t_{AS}$	0		_	ns
Address hold time	$t_{ m AH}$	10			ns
Data set-up time	$t_{ m DSW}$	40	_	_	ns
Data hold time	$t_{\mathrm{H}}$	10	_	_	ns

### 9.2 Read Operation

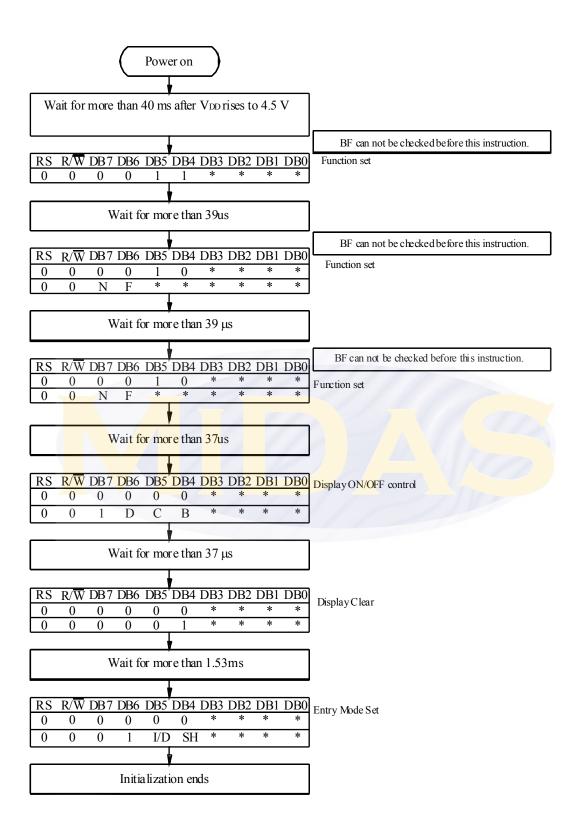


NOTE: \*VOL1 is assumed to be 0.8V at 2 MHZ operation.

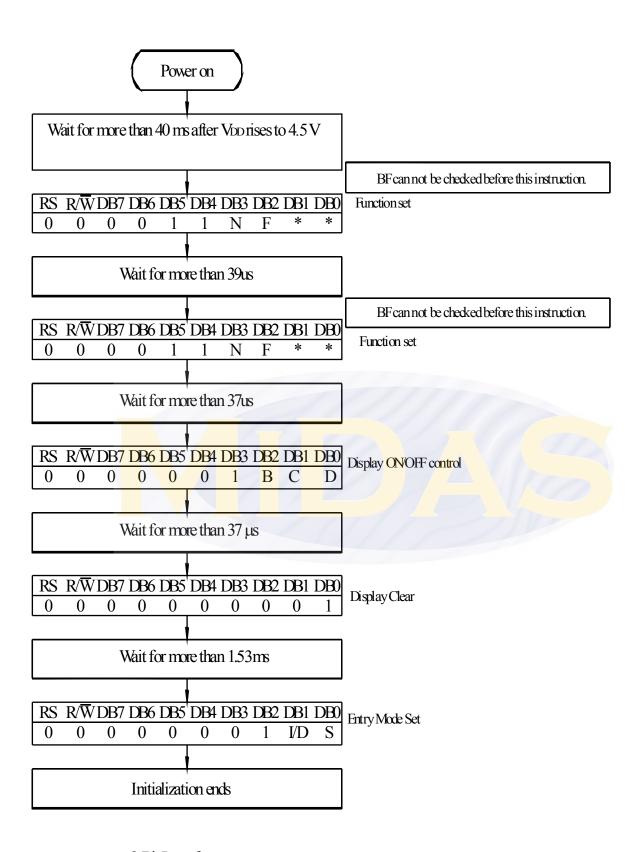
Ta=25°C, VDD=5.0 $\pm$  0.5V

Item	Symbol	Min	Тур	Max	Unit
Enable cyc <mark>le tim</mark> e	t <sub>cycE</sub>	1200			ns
Enable puls <mark>e widt</mark> h (h <mark>igh leve</mark> l)	$\overline{PW}_{EH}$	140	-		ns
Enable rise <mark>/fal</mark> l ti <mark>me</mark>	t <sub>Er</sub> ,t <sub>Ef</sub>	) <u> </u>		25	ns
Address set-up time (RS, R/W to E)	$t_{AS}$	0		/_1/	ns
Address hold time	$t_{AH}$	10	_	_	ns
Data delay time	t <sub>DDR</sub>	_	_	100	ns
Data hold time	t <sub>DHR</sub>	10	_	_	ns

### 10. Initializing of LCM



4-Bit Ineterface



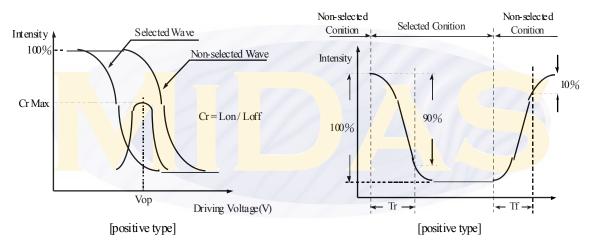
8-Bit Ineterface

### 11. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V) θ	CR≧2	20	_	40	deg
	(H) $\varphi$	CR≧2	-30	_	30	deg
Contrast Ratio	CR	_		3		_
Response Time	T rise	_		200	300	ms
1	T fall	_		200	300	ms

#### **Definition of Operation Voltage (Vop)**

#### Definition of Response Time (Tr, Tf)

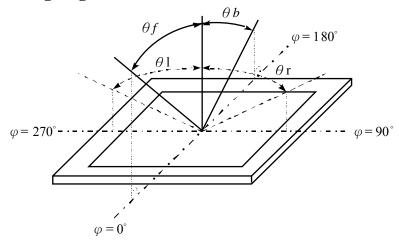


#### **Conditions:**

Operating Voltage: Vop Viewing Angle( $\theta$ ,  $\varphi$ ):  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

### Definition of viewing angle ( $CR \ge 2$ )



Page 17, Total 28 Pages

# 12. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	$T_{OP}$	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	$V_{\rm I}$	$V_{SS}$	_	$V_{DD}$	V
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	-0.3	_	7	V
Supply Voltage For LCD	$ m V_{DD} ext{-}V_0$	-0.3	_	13	V

### 13. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{\mathrm{DD}}$ - $V_{\mathrm{SS}}$		4.5	5.0	5.5	V
		Ta=-20°C	/-/	7	5.5	V
Supply Voltage For LCD	$V_{\rm DD}$ - $V_0$	Ta=25°℃	-//	4.5		V
	120	Ta=+70°C	3.8			V
Input High Volt.	$V_{IH}$	/ <del>/</del> //	$0.7 V_{DD}$		$V_{\mathrm{DD}}$	V
Input Low Volt.	$V_{ m IL}$	_	$V_{SS}$		0.6	V
Output High Volt.	$V_{\mathrm{OH}}$	_	3.9	_	_	V
Output Low Volt.	$V_{\mathrm{OL}}$	_			0.4	V
Supply Current	$I_{DD}$	$V_{DD}=5V$	1.0	1.2	1.5	mA

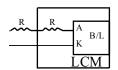
### 14. Backlight Information

### **Specification**

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
	BINDOL	17111	111	1717 171	OTTI	TEST CONDITION
Supply Current	ILED	28.8	32	50	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	${f v}$	
Reverse Voltage	VR	_	5	_	V	
<b>Luminous Intensity</b>	IV	210	230	_	CD/M <sup>2</sup>	ILED=32mA
Wave Length	λр				nm	ILED=32mA
Life Time			50K	_	Hr.	ILED=32mA
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

 $2.D\,rive\,\,from\,\,pin\,15\,,pin\,1\,6$ 



ill never get Vee output from pin 15)

### 15. Reliability

Content of Reliability Test (wide temperature, -20°C  $\sim$ 70°C)

	En vironmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	80°C 200hrs	2	
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C ,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 15mm  Vibration Frequency: 10~55Hz  One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

Note1: No dew condensation to be observed.

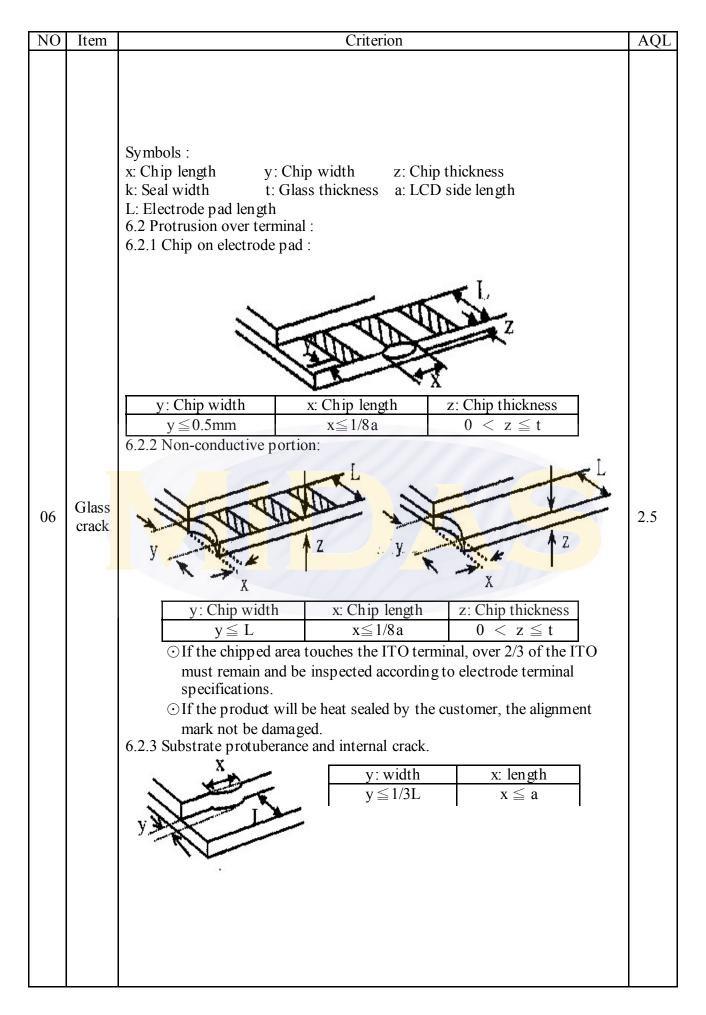
Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

# 16. Inspection specification

NO	Item	Criterion				
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ol>				
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>	2.5			
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x+y)/2$ $X$ $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$ 3.2 Line type : (As following drawing) $C = A $ $C = A $ $0.10 < \Phi \le 0.20$ $0.25 < \Phi$ $0$ 3.2 Line type : (As following drawing) $C = A $ $C$	2.5			
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5			

NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination	
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length:  6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:  z: Chip thickness y: Chip width x: Chip length  Z ≤ 1/2t Not over viewing area  1/2t < z ≤ 2t Not exceed 1/3k x ≤ 1/8a  olf there are 2 or more chips, x is total length of each chip.  6.1.2 Corner crack:  z: Chip thickness y: Chip width x: Chip length  Z ≤ 1/2t Not over viewing area  z: Chip thickness y: Chip width x: Chip length  X ≤ 1/8a  area	2.5
		$1/2t < z \le 2t \qquad \text{Not exceed } 1/3k \qquad x \le 1/8a$	
		$\odot$ If there are 2 or more chips, x is the total length of each chip.	



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.	0.65 2.5 0.65
		8.3 Backlight doesn't light or color wrong.	0.03
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>	2.5 0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		<ul><li>10.2 COB seal surface may not have pinholes through to the IC.</li><li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li></ul>	2.5 0.65
	PCB、COB	10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.	2.5
10		<ul><li>10.5 No oxidation or contamination PCB terminals.</li><li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing</li></ul>	2.5 0.65
		parts or excess parts.  10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		<ul> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> <li>10.9 The Scraping testing standard for Copper Coating of PCB</li> </ul>	2.5
		X 2	
		X * Y<=2mm <sup>2</sup>	2.5
			2.5
	Solder in g		2.5 0.65
11		<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	
		11.4 No short circuits in components on PCB.	

NO	Item	Criterion	AQL
12	General app earance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 LCD pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> <li>12.11 Product dimension and structure must conform to product specification sheet.</li> </ul>	2.5 0.65 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65

### 17. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.

### 18. Material List of Components for RoHs

1. T aaæ ÂÔ[{][}^} o Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs		
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm		
Above limited value is set up according to RoHS.								

#### 2.Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp.:

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°€, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

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MCT101E0CW1280800LMLIPS MCT104A0W1024768LML MCT070Z0W800480LML MCT0144C6W128128PML MCIB-16-LVDSCABLE MC41605A6W-FPTLA-V2 MCOT128064UA1V-WM MCT101E0TW1280800LMLIPS MCT150B0W1024768LML
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MC42005A12W-VNMLY MC42005A12W-VNMLG MCT052A6W480128LML MC21605A6WK-BNMLW-V2 MCOT256064A1A-BM
MCOT22005A1V-EYM MC20805A12W-VNMLG MC21605B6WD-BNMLW-V2 MC22405A6WK-BNMLW-V2 MC41605A6WKFPTLW-V2 MCT101HDMI-A-RTP MCT024L6W240320PML MCCOG21605D6W-FPTLWI MC21605A6WD-SPTLY-V2
MC22005A6WK-BNMLW-V2 MC24005AA6W9-BNMLW-V2 MC42004A6WK-SPTLY-V2 MC11609A6W-SPTLY-V2
MC07064048A1V-YM MCOT128064BY-BM MCCOG128064B12W-FPTLRGB MC11609A6W-SPR-V2 MC21605H6WK-BNMLW-V2
MCOT128064E1V-BM MCT070HDMI-B-RTP MDT5000C MCCOG42005A6W-BNMLWI